




## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-05-24
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Andrea Casali	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	true
	<b>Legal Declaration *</b> <b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN750PS-E	AJKU-VNE7X3A	A	SH1A	2013-05-24
Amount	UoM	Unit type	ST ECOPACK Grade	
80.52	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	4.60x3.90x1.52	8	flat	
Comment				

Material Composition Declaration						Mfr Item Name	AJKU-VNE7X3A					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	4.879	mg	supplier	die	Silicon (Si)	7440-21-3		4.711	mg	965567	58507
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	6764	410
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.033	mg	6764	410
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.03	mg	6149	373
die (s)				supplier	passivation	Indium Tin oxide ( In2O3.SnO2 )	50926-11-9		0.031	mg	6354	385
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	410	25
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1435	87
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.032	mg	6559	397
Leadframe	Copper & its alloys	33.676	mg	supplier	alloy	Copper (Cu)	7440-50-8		32.678	mg	970365	405837
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.769	mg	22835	9550
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.046	mg	1366	571
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.04	mg	1188	497
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.131	mg	3890	1627
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	119	50
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	119	50
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	119	50
Die attach		1.45	mg	supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.08	mg	55172	994
Die attach				supplier	glue or tape	Bismaleimide resin	Proprietary		0.058	mg	40000	720
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		1.312	mg	904828	16294
Bonding wire		0.281		supplier	wire	Gold (Au)	7440-57-5		0.281	mg	1000000	3490
encapsulation		40.233	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.023	mg	99993	49963
encapsulation				supplier	mold compound	phenol resin	9003-35-4		2.012	mg	50009	24988
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.402	mg	9992	4993
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		32.188	mg	800040	399752
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.804	mg	19984	9985
encapsulation				DIG I	mold compound	Brominated epoxy resin	68928-70-1		0.804	mg	19984	9985